

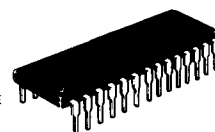


MEMORY ADDRESS MULTIPLEXER FOR 16K RAMS

- **Second Source to Intel 3242**
(Detect Zero Function Not Included and Additional Chip Enable Feature Added at Pin 15)

*See Pin Definitions

**SCHOTTKY
SILICON MONOLITHIC
INTEGRATED CIRCUITS**



•See Pin Definitions

Refresh Enable	Row Enable	Output
H	X	Refresh Address (From Internal Counter)
L	H	Row Address (A0 through A6)
L	L	Column Address (A7 through A13)

Count – Advances Internal Refresh Counter

Device	Temperature Range	Package
MC3242AL	0 to 75°C	Ceramic DIP
MC3242AP	0 to 75°C	Plastic DIP

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ADI-519

This is advance information and specifications are subject to change without notice.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

Rating	Symbol	Value	Unit
Power Supply Voltage	V_{CC}	-0.5 to +7.0	V
Input Voltage	V_I	-0.5 to +7.0	V
Output Voltage	V_O	-0.5 to +7.0	V
Output Current	I_O	100	mA
Operating Ambient Temperature	T_A	0 to +75	$^\circ\text{C}$
Storage Temperature	T_{stg}	-65 to +150	$^\circ\text{C}$
Junction Temperature	T_J		$^\circ\text{C}$
Ceramic Package		+175	
Plastic Package		+150	

"Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum ratings for extended periods may affect reliability.

ELECTRICAL CHARACTERISTICS (Unless otherwise noted, Min/Max values apply with $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$, $0^\circ\text{C} \leq T_A \leq 75^\circ\text{C}$; typical values apply with $V_{CC} = 5.0\text{ V}$, $T_A = 25^\circ\text{C}$.)

Characteristic	Symbol	Min	Typ	Max	Unit
Input Current, Low Logic State ($V_{IL} = 0.45\text{ V}$)	I_{IL}	—	-0.04	-0.25	mA
Input Current, High Logic State ($V_{IH} = 5.5\text{ V}$)	I_{IH}	—	—	10	μA
Input Voltage, Low Logic State	V_{IL}	—	—	0.8	V
Input Voltage, High Logic State	V_{IH}	2.0	—	—	V
Output Voltage, Low Logic State ($I_{OL} = 5.0\text{ mA}$)	V_{OL}	—	0.25	0.4	V
Output Voltage, High Logic State ($I_{OH} = -1.0\text{ mA}$)	V_{OH}	2.8	4.0	—	V
Input Clamp Voltage ($I_{IC} = -12\text{ mA}$)	V_{IC}	—	-0.8	-1.5	V
Power Supply Current ($V_{CC} = 5.5\text{ V}$)	I_{CC}	—	80	110	mA

SWITCHING CHARACTERISTICS (Unless otherwise noted, Min/Max values apply with $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$, $0^\circ\text{C} \leq T_A \leq 75^\circ\text{C}$; typical values apply with $V_{CC} = 5.0\text{ V}$, $T_A = 25^\circ\text{C}$.)

Characteristic	Symbol	Min	Typ	Max	Unit
Propagation Delay Times					
Address Input to Output (Load = 1 TTL, $C_L = 250\text{ pF}$) (Load = 1 TTL, $C_L = 15\text{ pF}$, $V_{CC} = 5.0\text{ V}$, $T_A = 25^\circ\text{C}$)	t_{AO}	— —	12 6.0	25 9.0	ns
Row Enable to Output (Load = 1 TTL, $C_L = 250\text{ pF}$) (Load = 1 TTL, $C_L = 15\text{ pF}$, $V_{CC} = 5.0\text{ V}$, $T_A = 25^\circ\text{C}$)	t_{OO}	— —	32 18	41 27	ns
Refresh Enable to Output (Load = 1 TTL, $C_L = 250\text{ pF}$) (Load = 1 TTL, $C_L = 15\text{ pF}$, $V_{CC} = 5.0\text{ V}$, $T_A = 25^\circ\text{C}$)	t_{EO}	— —	32 18	45 27	ns
Count Pulse Width	t_{WC}	30	—	—	ns
Counting Frequency	f_C	5.0	10	—	MHz



FIGURE 1 — AC WAVEFORMS WITH MCM4116 NORMAL CYCLE

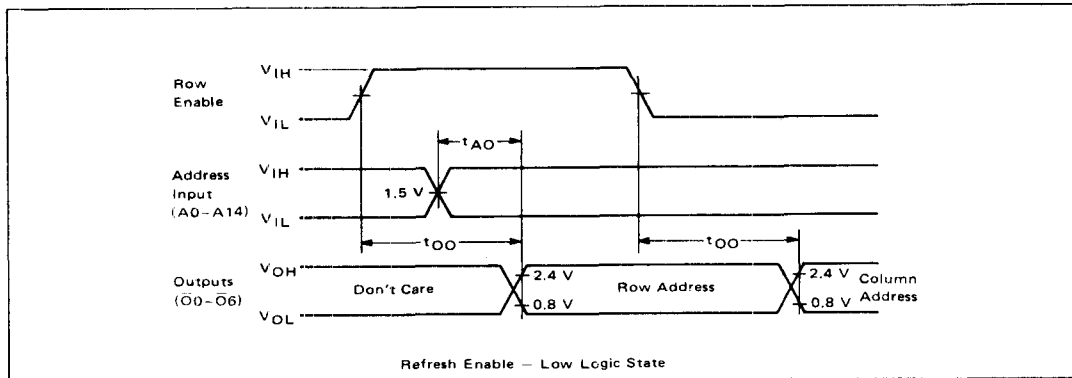
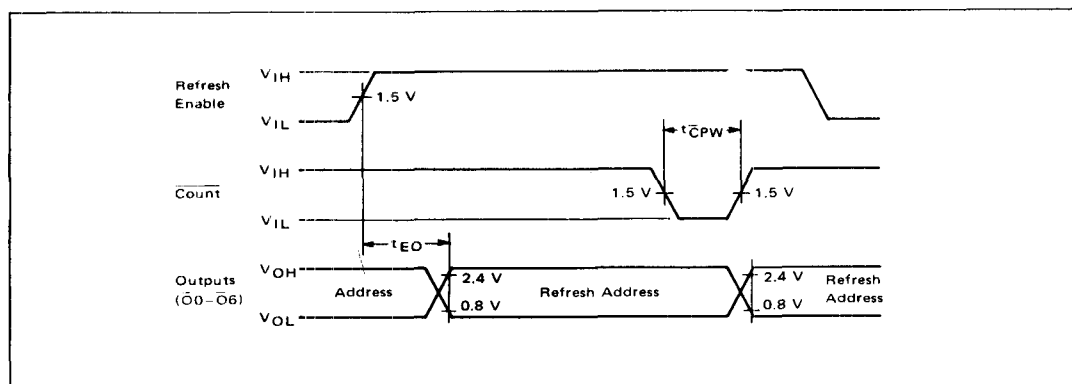
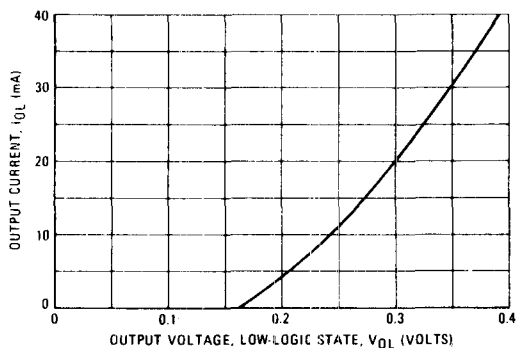
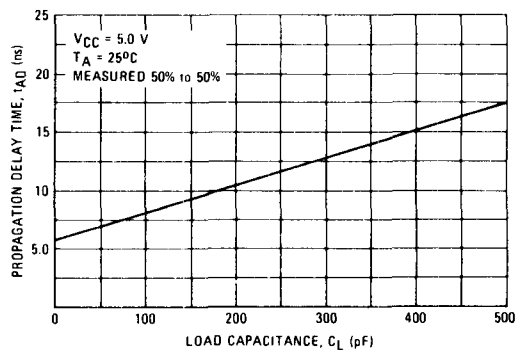


FIGURE 2 — REFRESH CYCLE



TYPICAL CHARACTERISTICS

FIGURE 3 — OUTPUT CURRENT versus OUTPUT LOW VOLTAGE

FIGURE 4 — PROPAGATION DELAY versus LOAD CAPACITANCE
Row or Column Address to Output

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PIN DEFINITIONS

Count Input – Pin 1

Active low input increments internal 6-bit counter by one for each count pulse in.

Refresh Enable Input – Pin 2

Active high input which determines whether the MC3242A is in refresh mode (H) or address enable (L).

A0–A6 Inputs – Pins 9, 5, 7, 21, 23, 27

Row address inputs.

A7–A13 Inputs – Pins 10, 6, 8, 20, 22, 24, 26

Column address inputs.

 $\bar{O}0$ – $\bar{O}6$ Outputs – Pins 11, 12, 13, 18, 17, 16, 19

Address outputs to memories. Inverted with respect to address inputs.

Gnd – Pin 14

Power supply ground.

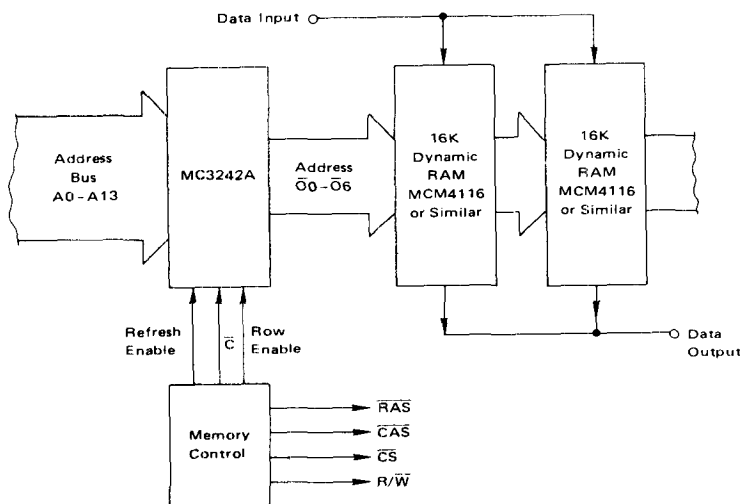
CE Input – Pin 15

Optional use, chip enable control pin. Left open, an internal 50 k Ω pullup resistor keeps this pin high and the MC3242A is a functional replacement for the Intel 3242 (without detect zero function). As an active input, when pulled low, all 3242A outputs go three-state. Regardless of Pin 15 (CE) condition, when power (V_{CC}) is removed, all 3242A outputs go three-state. In addition, the refresh address counter is reset to all 1s so that upon return of supply power, control of refresh addressing can be returned to the MC3242A (by pulling Pin 15 high) at a known address (i.e., all 1s). This option is available tested by consulting factory.

 V_{CC} – Pin 28

+5 V power supply input. Due to high capacitance drive capability, a 0.1 μ F capacitor should be used to ground along with careful V_{CC} and Gnd Bus layout.

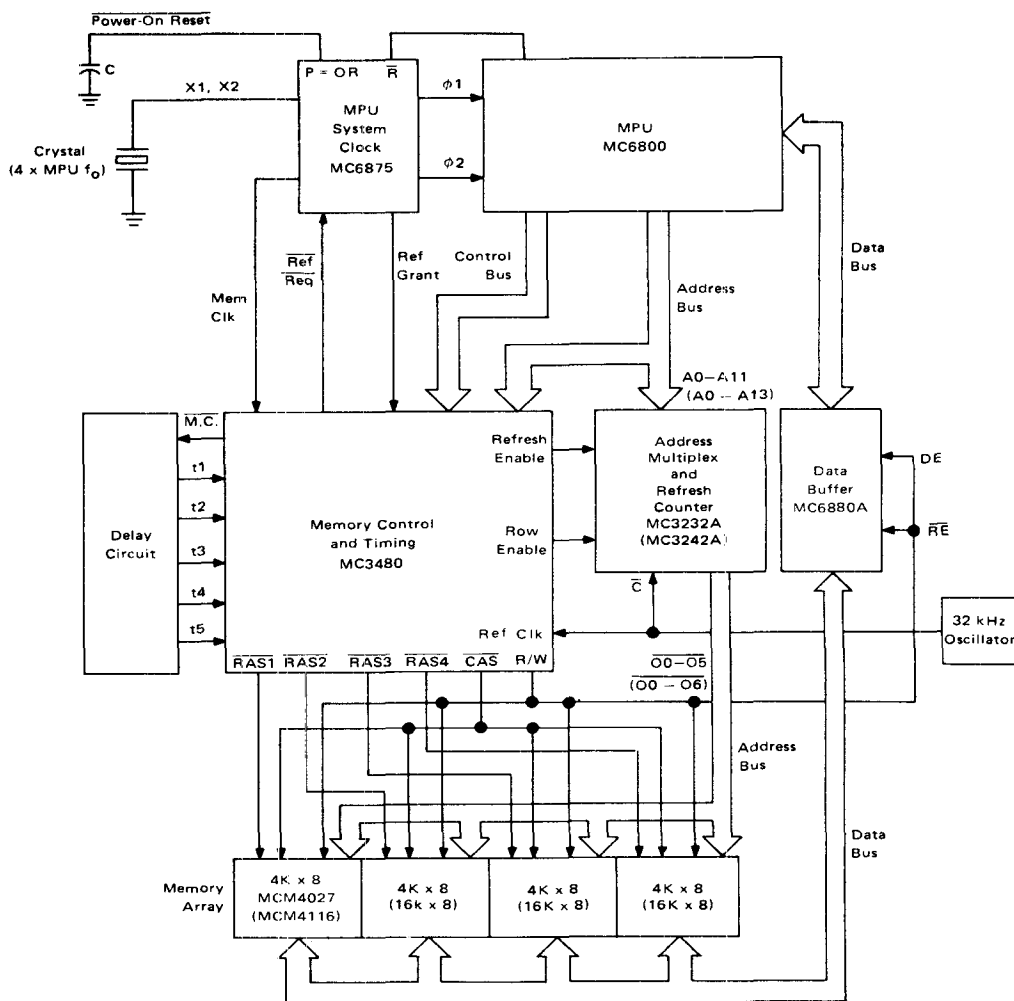
GENERAL 16K DYNAMIC RAM
SIMPLIFIED BLOCK DIAGRAM



MOTOROLA Semiconductor Products Inc.

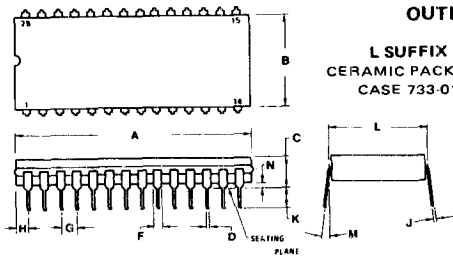
TYPICAL APPLICATION **16K X 8-BIT MEMORY SYSTEM FOR M6800 MPU**

Note: Numbers in parenthesis indicate part types or values for 16K x 1 RAMs



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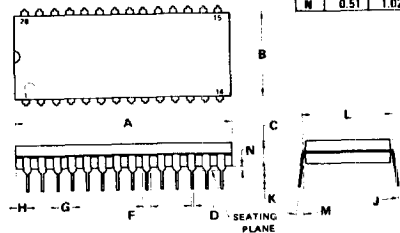
OUTLINE DIMENSIONS

L SUFFIX
 CERAMIC PACKAGE
 CASE 733-01


DIM	MIN	MAX	MIN	MAX
A	36.83	37.59	1.450	1.480
B	12.70	12.46	0.500	0.530
C	5.08	5.84	0.200	0.230
D	0.38	0.56	0.015	0.022
F	1.27	1.95	0.050	0.085
G	2.54	BSC	0.100	BSC
H	2.03	2.79	0.080	0.090
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	15.24	BSC	0.600	BSC
M	5°	15°	5°	15°
N	0.51	1.27	0.020	0.050

NOTES:

1. LEADS WITHIN 0.25 mm (0.010) DIA OF TRUE POSITION OF SEATING PLANE, AT MAXIMUM MATERIAL CONDITION
2. DIM L TO CENTER OF LEADS WHEN FORMED PARALLEL
3. DIM A AND B INCLUDES MENISCUS

P SUFFIX
 PLASTIC PACKAGE
 CASE 710-01


DIM	MIN	MAX	MIN	MAX
A	36.32	37.34	1.430	1.470
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54	BSC	0.100	BSC
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24	BSC	0.600	BSC
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

THERMAL INFORMATION

The maximum power consumption an integrated circuit can tolerate at a given operating ambient temperature, can be found from the equation:

$$P_D(T_A) = \frac{T_J(\max) - T_A}{R_{\theta JA}(\text{Typ})}$$

Where: $P_D(T_A)$ = Power Dissipation allowable at a given operating ambient temperature. This must be greater than the sum of the products of the supply voltages and supply currents at the worst case operating condition.

$T_J(\max)$ = Maximum Operating Junction Temperature as listed in the Maximum Ratings Section

T_A = Maximum Desired Operating Ambient Temperature

$R_{\theta JA}(\text{Typ})$ = Typical Thermal Resistance Junction to Ambient

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311-K78/3.5

Printed in Switzerland